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RELIABILITY REPORT  
FOR

DS21Q59, Rev A2

Dallas Semiconductor

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**Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

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In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at <http://www.maxim-ic.com/TechSupport/dsreliability.html>.

**Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at [http://dbserv.maxim-ic.com/l\\_datasheet3.cfm](http://dbserv.maxim-ic.com/l_datasheet3.cfm).

**Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

$AfT = \exp((Ea/k) * (1/Tu - 1/Ts)) = tu/ts$   
AfT = Acceleration factor due to Temperature  
tu = Time at use temperature (e.g. 55°C)  
ts = Time at stress temperature (e.g. 125°C)  
k = Boltzmann's Constant ( $8.617 \times 10^{-5}$  eV/°K)  
Tu = Temperature at Use (°K)  
Ts = Temperature at Stress (°K)  
Ea = Activation Energy (e.g. 0.7 eV)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7eV will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

$AfV = \exp(B * (Vs - Vu))$   
AfV = Acceleration factor due to Voltage  
Vs = Stress Voltage (e.g. 7.0 volts)  
Vu = Maximum Operating Voltage (e.g. 5.5 volts)  
B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.)

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

$Fr = X / (ts * AfV * AfT * N * 2)$   
X = Chi-Sq statistical upper limit  
N = Life test sample size

Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

$MTTF = 1/Fr$

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

**FAILURE RATE:**                      **MTTF (YRS): 41831**                      **FITS: 2.7**

The parameters used to calculate this failure rate are as follows:

**Cf: 60%**                      **Ea: 0.7**                      **B: 0**                      **Tu: 25 °C**                      **Vu: 5.5 Volts**

The reliability data follows. A the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available.

**Device Information:**

Process: D6H-2P2M,HPVt,TCZ ALOCOS:GOI  
Passivation: Laser/TEOS Ox - Pass/Nit - Gen.LaserPrb  
Die Size: 409 x 407  
Number of Transistors: 800000  
Interconnect: Aluminum / 1% Silicon / 0.5% Copper  
Gate Oxide Thickness: 150 Å

**ELECTRICAL CHARACTERIZATION**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
ESD SENSITIVITY	0311	EOS/ESD S5.1 HBM 500 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0311	EOS/ESD S5.1 HBM 1000 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0311	EOS/ESD S5.1 HBM 2000 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0311	EOS/ESD S5.1 HBM 4000 VOLTS	1 PUL'S	3	0
ESD SENSITIVITY	0311	EOS/ESD S5.1 HBM 8000 VOLTS	1 PUL'S	3	3
LATCH-UP	0311	JESD78, I-TEST 125C		6	0
LATCH-UP	0311	JESD78, Vsupply TEST 125C		6	0
Total:					3

**OPERATING LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
HIGH VOLTAGE LIFE	0227	125C, 6.0 VOLTS	1000 HRS	77	0
HIGH VOLTAGE LIFE	0307	125C, 6.0 VOLTS	1000 HRS	77	0
HIGH VOLTAGE LIFE	0310	125C, 6.0 VOLTS	1000 HRS	80	0
HIGH TEMP OP LIFE	0311	125C, 3.5 VOLTS	1000 HRS	77	0
HIGH TEMP OP LIFE	0312	125C, 3.3 VOLTS	1000 HRS	45	0
Total:					0

**STORAGE LIFE**

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
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STORAGE LIFE	0305	125C	1000 HRS	45	0
STORAGE LIFE	0309	125C	1000 HRS	45	0
STORAGE LIFE	0312	125C	1000 HRS	42	0
STORAGE LIFE	0312	125C	1000 HRS	41	0
STORAGE LIFE	0312	150C	1000 HRS	77	0
STORAGE LIFE	0330	125C	1000 HRS	45	0
<b>Total:</b>					<b>0</b>

#### TEMPERATURE CYCLE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
TEMP CYCLE	0305	-55C TO 125C	1000 CYS	45	0
TEMP CYCLE	0309	-55C TO 125C	1000 CYS	45	0
TEMP CYCLE	0310	-55C TO 125C	1000 CYS	80	0
TEMP CYCLE	0312	-55C TO 125C	1000 CYS	45	0
TEMP CYCLE	0312	-55C TO 125C	1000 CYS	45	0
TEMP CYCLE	0312	-55C TO 125C	1000 CYS	76	0
TEMP CYCLE, SLOW	0330	-40C TO +125C	1000 CYS	45	0
<b>Total:</b>					<b>0</b>

#### UNBIASED MOISTURE RESISTANCE

DESCRIPTION	DATE CODE	CONDITION	READPOINT	QUANTITY	FAILS
MOISTURE SOAK	0305	85 C/85% R.H.	1000 HRS	45	0
MOISTURE SOAK	0309	85 C/85% R.H.	1000 HRS	45	0
MOISTURE SOAK	0312	85 C/85% R.H.	1000 HRS	45	0
MOISTURE SOAK	0312	85 C/85% R.H.	1000 HRS	45	0
HAST	0312	130C, 85% R.H.	96 HRS	45	0
MOISTURE SOAK	0330	85 C/85% R.H.	1000 HRS	45	0
<b>Total:</b>					<b>0</b>

**FAILURE RATE:**

**MTTF (YRS): 41831**

**FITS: 2.7**